



**EXPEDITED PROCEDURE - EXAMINING GROUP 2814**

**S/N 09/259,849**

**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant:	Paul A. Farrar	Examiner:	Ginette Peralta
Serial No.:	09/259,849	Group Art Unit:	2814
Filed:	March 1, 1999	Docket:	303.557US1
Title:	CONDUCTIVE STRUCTURES IN INTEGRATED CIRCUITS		

**AMENDMENT & RESPONSE UNDER 37 C.F.R. § 1.116**

Box AF  
Commissioner for Patents  
Washington, D.C. 20231

In response to the final office action mailed December 7, 2001, please amend the application as follows:

**IN THE CLAIMS**

Please substitute the claim set in the appendix entitled Clean Version of Pending Claims for the previously pending claim set. The substitute claim set is intended to reflect amendment of previously pending claims 1, 4, 8, 12, 15, 19, 23, 27, 30, 34, 38, 42, 45, 50, 56 and 67. The specific amendments to individual claims are detailed in the following marked up set of claims.

1.(Amended) A method of forming a conductor comprising:

- depositing an insulator over a planarized surface;
- etching a trench having a depth on the insulator;
- depositing a barrier layer on the insulator;
- depositing a seed layer on the barrier layer;
- removing the barrier layer and seed layer from selected areas of the insulator, leaving a seed area; and

depositing a conductor on the seed area by a selective deposition process after removing the barrier layer and seed layer from selected areas of the insulator.